



Open-molded Plastic Packages (OmPP)



Advantages:

- Larger Die Paddle Area
- Supports larger die and ground bonds per given body size
- RoHS and REACH Compliant "Green" Molding Compound
- Gold Plated
- Superior Bondability
- Custom Body Sizes and Lead Counts Available

Quik-Pak announces the exclusive Open-molded Plastic Package (OmPP)™ for your packaging needs. From prototype to production volumes, these pre-molded QFN packages, created by Quik-Pak, provide a high quality, fast solution for your assembly needs.

Pre-Molded Packages offer Flexibility

Quik-Pak's pre-molded packages come in a variety of sizes. They are available from 3x3mm to 12x12mm body size with lead pitch sizes ranging from 0.80mm to 0.40mm. Covers or lids are also available for air cavity applications.

Quik-Pak has been a standard part of your product development process for over 15 years, providing Open Cavity Plastic Package (OCP), custom packaging and assembly solutions. The Open-molded Plastic Packages (OmPP) solution offers production quality premolded packages, flexibility and rapid delivery to meet your needs.

Quik-Pak offers a turnkey assembly solution including:

- Wafer Dicing
- Wire Bonding
- Custom Packaging
- Backgrinding
- Complete Assembly
- Patented Open Cavity Plastic Package (OCP)

Quik-Pak™

Microelectronic Packaging & Assembly Solutions

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As a leader in quick-turn assembly, Quik-Pak provides dependable customer service with every order. The company also provides application engineering support to optimize your assembly process. Whether bondability, dispensing materials, or package customization, the Quik-Pak staff has the expertise to assist you with any project.

Samples are available upon request. Please visit www.icproto.com or contact us at (858) 674-4676.